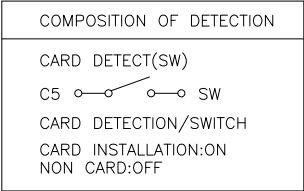
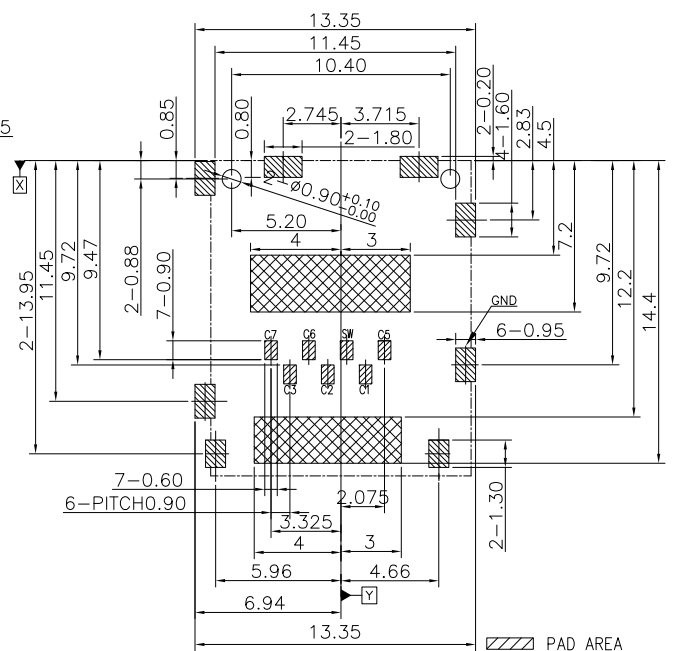
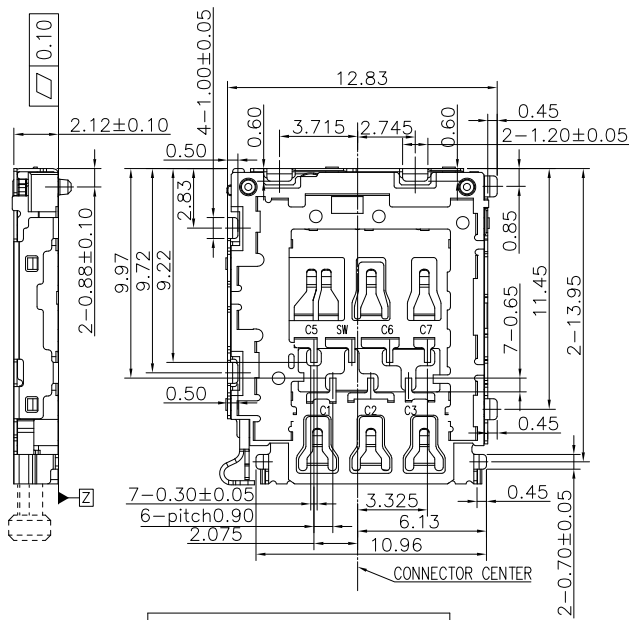
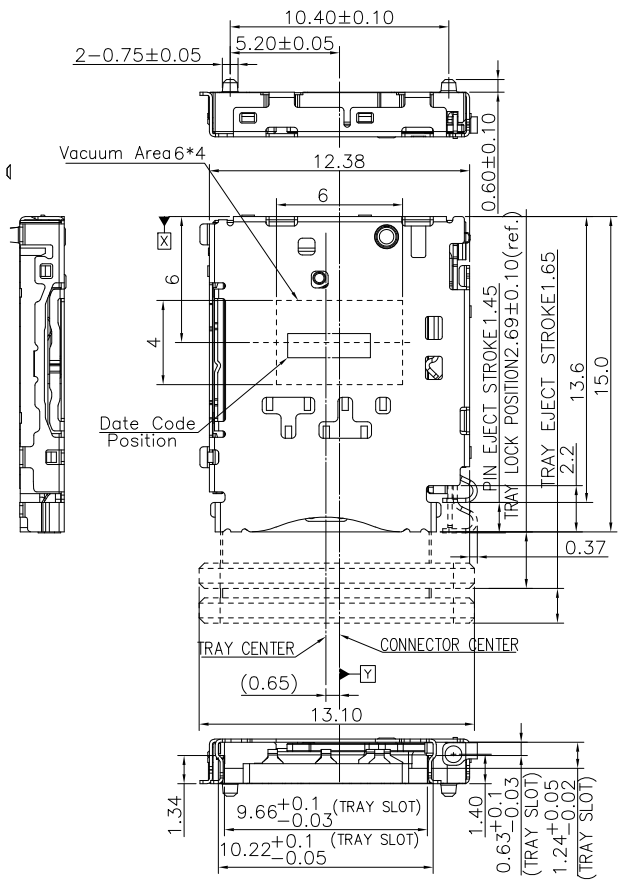


REVISION HISTORY			
REV	DESCRIPTION	Drawing	DATE
02	修改TITLE说明	Allen	2020/08/17



RECOMMEND P.C.B LAYOUT
(General tolerance ±0.05)

- PAD AREA
- KEEP OUT AREA
- NO COPPER AREA (NO Trace&Via&GND)
- GND PATTERN ONLY

NOTE:

1. MATERIAL:

1.1 HOUSING: HIGH TEMPERATURE THERMOPLASTIC, UL94V-0, COLOR:BLACK

1.2 CONTACT: COPPER ALLOY.

1.3 COVER: MATAL.

2. FINISH:

2.1 CONTACT:

CONTACT AREA: G/F

SOLDER AREA: G/F

UNDERPLATING: Ni OVER ALL 50 u" Min.

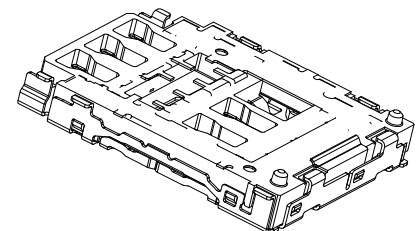
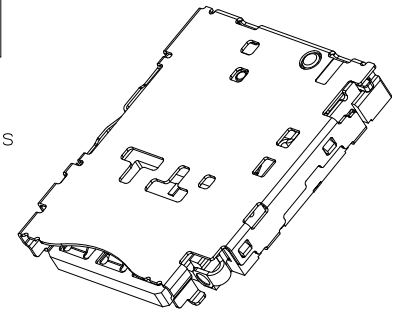
2.2 COVER

SOLDER AREA: G/F

UNDERPLATING: Ni OVER ALL 30 u" Min.

SIM Card Pin Assignments

NANO SIM CARD	
C1	Vcc
C2	RST
C3	CLK
C5	GND
SW	CD/SW
C6	Vpp
C7	DATA



PRODUCT SPECIFICATION: DOC.No: SP-AXXXX-XX	SCALE 1 : 1	DESIGN UNITS mm
TEST REPRDT DOC.No: TR-AXXXX-XX	DRAWN Allen	DATE 2020/02/21
GENERAL TOLERANCES (UNLESS SPECIFIED)	CHECKED	DATE
X.XXX ± 0.20	APPROVED	DATE
X.XX ± 0.20		
X.X ± 0.25		
ANGULAR ± 3°		
THIRD ANGLE PROJECTION	DWG NO. SA0801-001	PART NO. A0801-0001

FULLINHOPE Technology, LTD.

NANO SIM Tray Ejected Pin

DWG REV. 02	SHEET NO. 1 OF 1
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